

**METHOD FOR FORMING OPENINGS IN A SUBSTRATE
USING A PACKING AND UNPACKING PROCESS**

ABSTRACT

[0041] A method and system is disclosed for selectively forming photoresist patterns for making openings in a substrate. A layer of photoresist is deposited on the substrate which contains one or more types of photoresist dissolving agent generators. A first set of areas of the photoresist is exposed to a first light source through a first mask to activate a photoresist dissolving agent generator of a first type to release a first photoresist dissolving agent in the first set of areas. Then, a second set of areas of the photoresist is also exposed to a second light source through a second mask to activate a photoresist dissolving agent generator of a second type to release a second photoresist dissolving agent in the second set of areas. The second set of areas is a sub set of the first set of areas such that the first and second photoresist dissolving agents in the second set of areas neutralize each other to protect the second set of areas from being used as the patterns for forming the openings.